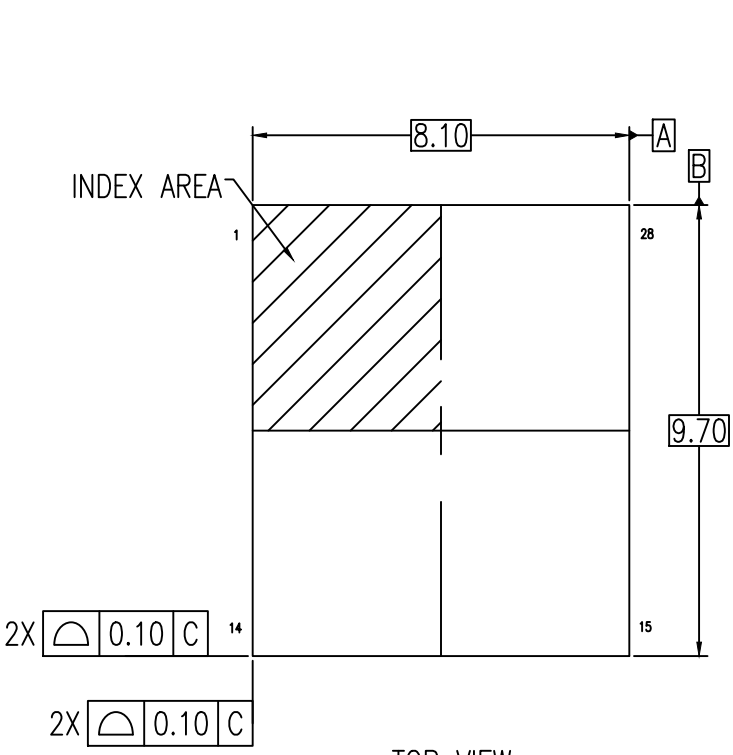
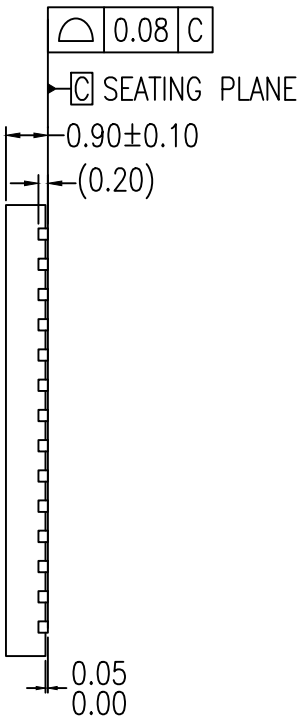
28-DFN, Package Outline Drawing

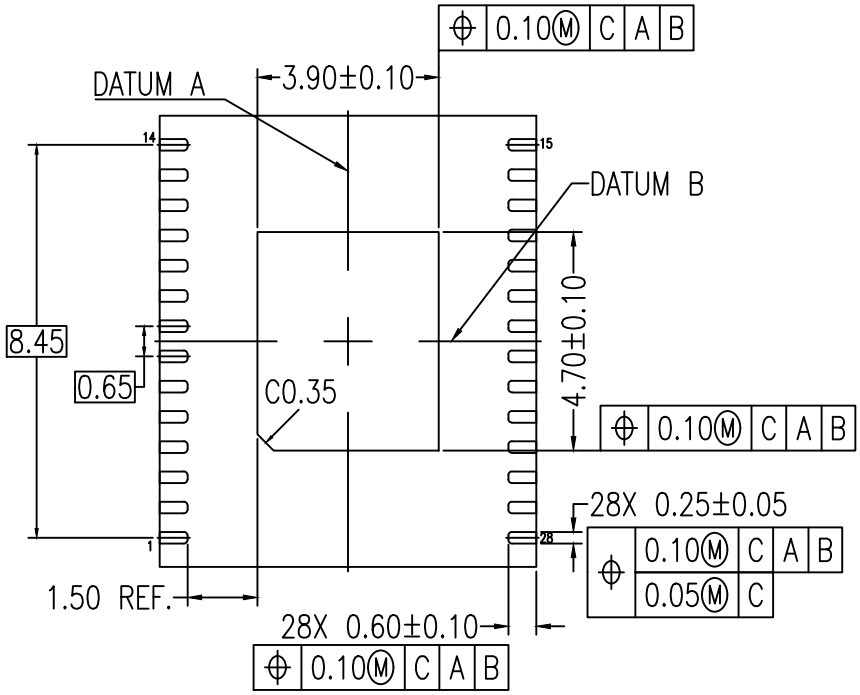
8.10 x 9.70 x 0.90 mm Body, 3.90 x 4.70 mm Epad, 0.65mm Pitch



TOP VIEW



SIDE VIEW



BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5–2009
2. ALL DIMENSIONS ARE IN MILLIMETERS

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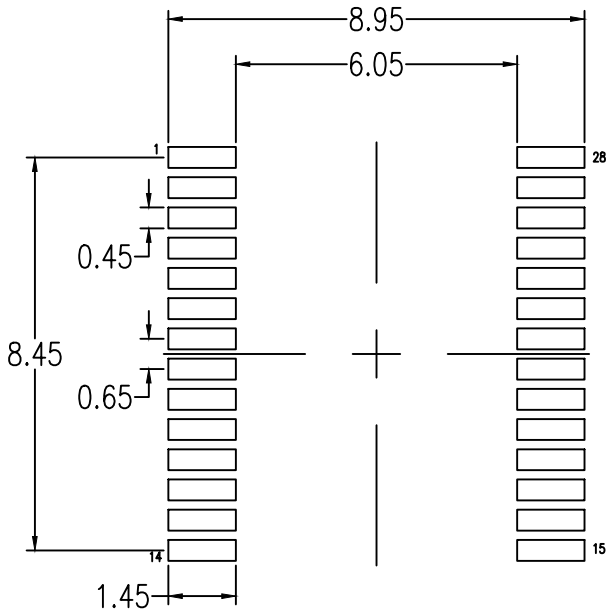

RECOMMENDED LAND PATTERN DIMENSION

NOTES:
1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES.
2. TOP DOWN VIEW. AS VIEWED ON PCB.
3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.
4. NSMD PATTERN ASSUMED.

Package Revision History		
Date Created	Rev No.	Description
Sep 11, 2019	00	Initial Release

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